

ALD precursors	Note
TMA	For Al <sub>2</sub> O <sub>3</sub> films
TiCl <sub>4</sub>	For TiO <sub>2</sub> films
Electron beam evaporator pellets	Note
Al Cr Cu Ni Ti	For Lesker EBE1 and EBE2 tools
Etchants	Note
Al etchant	<a href="https://www.alfa.com/en/catalog/044581/">https://www.alfa.com/en/catalog/044581/</a>
Buffered oxide etchant 7:1 (BoE)	
Cr etchant	<a href="https://www.alfa.com/en/catalog/044582/">https://www.alfa.com/en/catalog/044582/</a>
Cu etchant	<a href="https://www.alfa.com/en/catalog/044583/">https://www.alfa.com/en/catalog/044583/</a>
Liquid chemicals	Note
Acetone Hydrochloric acid (HCl) Hydrofluoric acid 49% (HF) Hydrogen peroxide 30% Isopropyl alcohol (IPA) Methanol Sulfuric acid (H <sub>2</sub> SO <sub>4</sub> )	
Photoresists	Note
HMDS adhesion promoter Shipley 1818 AZ5214 950 PMMA A4 494 PMMA A4 PGMEA	For Suss and EVG 610 mask aligners For Suss and EVG 610 mask aligners For electron beam lithography For electron beam lithography
Nanoscribe resins	Note
IP-Visio Photoresist IP-Q Photoresist IP-Dip Photoresist IP-L Photoresist IP-S Photoresist	
Lithography developers and strippers	Note
TMAH 25% in water AZ 400T stripper AZ developer 1:1 AZ 300 MIF developer AZ 726 MIF developer AZ 400K (1:4) developer MIBK/IPA developer MIF-319 developer KAM Remover PG	
Sputter Targets	Note
Au	For Cressington sputter coater
Al Cr Cu Ni Ti	For Lesker PVD75 DC tool
SiO <sub>2</sub>	For Lesker PVD75 RF tool
Al Al <sub>2</sub> O <sub>3</sub> Cu Hf Ir NbO <sub>2</sub> Nb <sub>2</sub> O <sub>5</sub> Pt Si SiO <sub>2</sub> Ta Ti TiN TiO <sub>2</sub>	For Clustex

Ru  
V205  
VO2  
W